Title (en)

HEAT-SINKING STRUCTURES AND ELECTRICAL SOCKETS FOR USE THEREWITH

Title (de)

KUHLSTRUKTUREN UND ELEKTRISCHE STEERDOSEN IN VERBINDUNG DAMIT

Title (fr)

STRUCTURES DE DISSIPATION DE CHALEUR ET DOUILLES ELECTRIQUES UTILISEES AVEC DE TELLES STRUCTURES

Publication

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Application

EP 96909496 A 19960221

Priority

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Abstract (en)

[origin: WO9626030A1] A process of making a heat-sinking structure (5), which includes providing a mold (15) having cavities (12a) closed at one end and open at another end, the cavities (12a) corresponding to the heat dissipating surfaces on the heat-sinking structure (5), at least partially evacuating ambient gases from the cavities (12a), filling the mold (15) with molten material, and solidifying the same to form the heat-sinking structure (5). A combination structure of electromagnetic interference filter (130) and electrical socket assembly (128, 132) includes an electromagnetic interference filter (130), at least one terminal blade (118) passing through the electromagnetic interference filter (130), and a block of electrically insulating material (126). The terminal blade (118) provides an electrically conductive path and a connection mechanism configured to inter-fit with another electrical conductor. The electromagnetic filter (130) comprising the terminal blade (118) is molded into the electrically insulating material (126) to form an electrical socket (128, 132). The terminal blade (118) passes trough the electrically insulating material (126) and has exposed ends.

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B22D 18/06; H01R 13/10

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